

Integrated AC LED Solution

Acrich3 - 16.6W SMJD-XD16W4PX









### **Product Brief**

### **Description**

- The Acrich3 series of products are designed to be driven directly off of AC line voltage, therefore they do not need the standard converter essential for conventional general lighting products.
- The converter or driver found in most general lighting products can limit the overall life of the product, but with the Acrich3 series of products the life of the product can more closely be estimated from the LED itself. This will also allow for a much smaller form factor from an overall fixture design allowing for higher creativity in the fixture.
- The modules have a high power factor which can contribute to a higher energy savings in the end application.

### **Features and Benefits**

- Connects directly to AC line voltage
- High Power Efficiency & Factor
- Low THD
- Long Life Time
- Simple BOM
- Miniaturization
- Lead Free Product
- RoHS Compliant
- TRIAC Dimming

### **Key Applications**

Down Llight

Table 1. Product Selection (CCT)

Part No.	Vin [Vac]	P [W]	Color	сст [к]	CRI Min.
SMJD-2D16W4PD	120		Cool	4700 – 6000	80
SMJD-3D16W4PD	220	16.6	Neutral	3700 – 4200	
SMJD-2D16W4PE	120	10.0		0700 4200	- 00
SMJD-3D16W4PE	220		Warm	2600 - 3200	90

Table 2. Product Selection (Flux)

Part No.	Vin [Vao]	D IWI	Flux	Flux [lm]			
Fait No.	Vin [Vac]	P [W]	Min.	Тур.	Remark		
01110 0010111100	400		1350	1450	16a		
SMJD-2D16W4PD SMJD-3D16W4PD	120 220	16.6	1450	1600	16b		
01100 05 1011 11 5			1600	1750	16c		
SMJD-2D16W4PE SMJD-3D16W4PE	120 220	16.6	1250	1350	16a		

# **Table of Contents**

Index	(	
•	Product Brief	1
•	Table of Contents	2
•	Performance Characteristics	3
•	Thermal Resistance	5
•	Characteristic Graph	6
•	Color Bin Structure	11
•	Mechanical Dimensions	17
•	Marking Information	19
•	Packing Information	20
•	Label Information	21
•	Handling of Silicone Resin for LEDs	22
•	Precaution for Use	23
•	Company Information	25

### **Performance Characteristics**

Table 3. Electro Optical Characteristics, T<sub>a</sub> = 25°C

	0		Value		1152	Marila
Parameter	Symbol	Min.	Тур.	Max.	Unit	Mark
		1350	1450	-		16a
Luminous Flux (@CRI.80)		1450	1600	-	-	16b
(00100)	$\Phi_V^{[2]}$	1600	1750	-	lm	16c
Luminous Flux (@CRI.90)	•	1250	1350	-	-	16a
		5300	5600	6000		В
		4700	5000	5300	-	С
Correlated Color Temperature [3]	CCT	3700	4000	4200	K	E
		2900	3000	3200	-	G
		2600	2700	2900	_	Н
CRI	Ra	80	-	-	-	PD
CKI	Ka	90	-	-	-	PE
Innut Voltage [4]	V		120		\/00	2D
Input Voltage [4]	$V_{in}$		220		- Vac	3D
Power Consumption	Р	14.9	16.6	18.3	W	16W
Operating Frequency	F		50 / 60		Hz	
Power Factor	PF		Over 0.97		-	
Viewing Angle	2O <sub>1/2</sub>		120	·	deg.	
Tolerance of Surge [5]	V <sub>s</sub>	500	-	-	V	
Transient Protection [6]	V <sub>s</sub>	2500	-	-	V	

#### Notes:

- (1) At 120/220Vac, T<sub>a</sub> = 25°C
- (2)  $\Phi_V$  is the total luminous flux output measured with an integrated sphere.
- (3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- (4) Operating Voltage doesn't indicate the maximum voltage which customers use but means tolerable voltage according to each country's voltage variation rate. It is recommended that the solder pad temperature should be below 70 °C.
- (5) Surge withstand in accordance with IEC61000-4-5
- (6) At 120Vac, seven strikes, 100kHz 2.5kV in accordance with ANSI/IEEE C62.41.2-2002 Category A operation



## **Performance Characteristics**

Table 4. Absolute Maximum Ratings,  $T_a = 25^{\circ}C$ 

Parameter	Symbol	Unit	Value
Maximum Input Voltage @120Vac	V	\/	144
Maximum Input Voltage @220Vac	$V_{in}$	Vac	264
Power Consumption	Р	W	21.5
Operating Temperature	$T_{opr}$	°C	-30 ~ 85
Storage Temperature	T <sub>stg</sub>	°C	-40 ~ 100
ESD Sensitivity	-	-	±4,000V HBM

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### **Thermal Resistance**

Part	Package Power Dissipation [W]	Maximum Junction Temperature [℃]	Rθ <sub>j-s</sub> [℃/W]
Acrich3 LED	SAW8C72A Max 1.5	125	0
ACTIONS LED	SAW9C72A Max 1.5	125	9

#### Notes:

The Acrich3 LED has a thermal resistance of  $9\,^\circ\text{C/W}$  from junction of the LED to the

LED lead.

The maximum junction temperature of the Acrich3 LED package is 125  $^{\circ}$ C, therefore the maximum lead temperature T<sub>s max</sub> is

$$T_{s_{max}} = T_{j_{max}} - (R\theta_{j-s} * P_d)$$
  
= 125°C - (9°C/W \* 1.5W) = 111.5°C

Although this is the maximum lead temperature, it is recommended to keep the lead temperature under 70  $^{\circ}$ C.

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Fig 1. Relative Spectral Distribution vs. Wavelength Characteristic - G, H

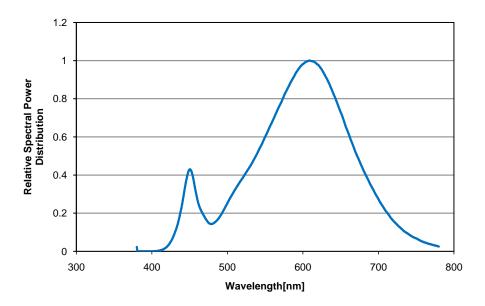


Fig 2. Relative Spectral Distribution vs. Wavelength Characteristic - E

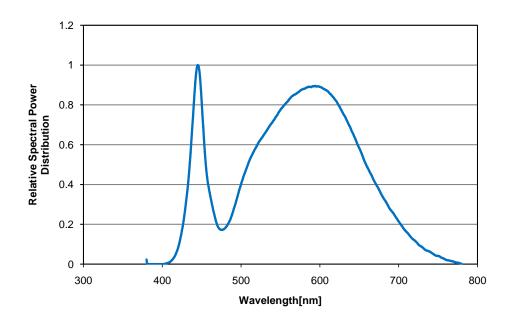


Fig 3. Relative Spectral Distribution vs. Wavelength Characteristic - B,C

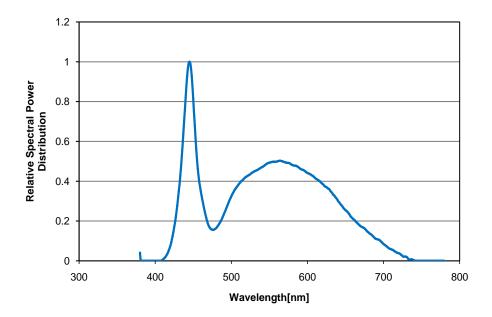


Fig 4. Relative Power Distribution vs. Voltage at  $T_a = 25 \, ^{\circ} \! \text{C}$ , 120V

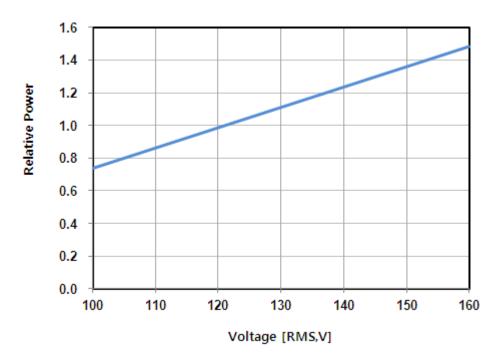


Fig 5. Relative Power Distribution vs. Voltage at  $T_a = 25 \, ^{\circ} \! \text{C}$ , 220V

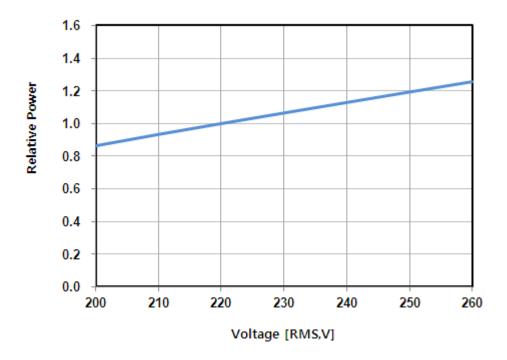


Fig 6. Relative Luminous Flux vs. Voltage at  $T_a = 25 \, ^{\circ} \text{C}$ , 220V

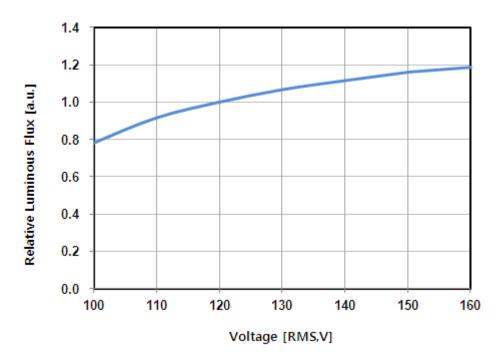


Fig 7. Relative Luminous Flux vs. Voltage at  $T_a = 25 \, ^{\circ}\mathrm{C}$ , 220V

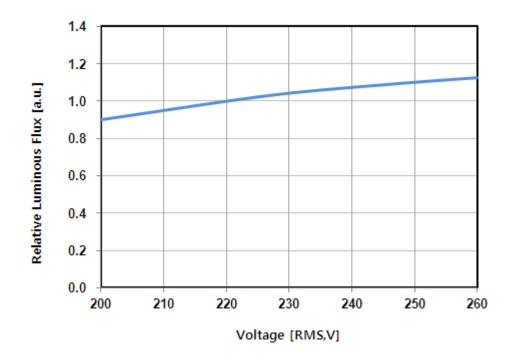
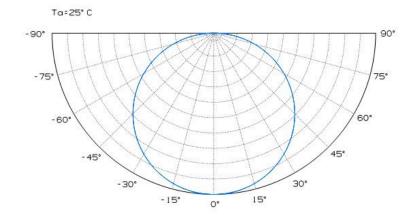
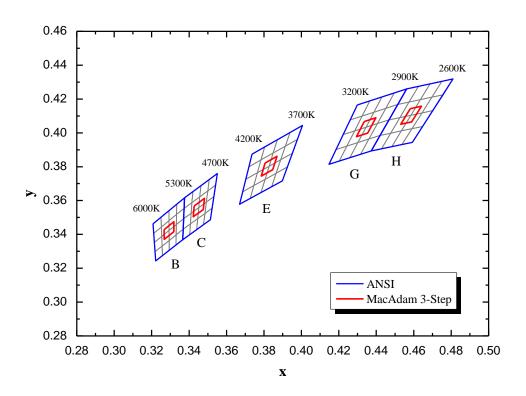
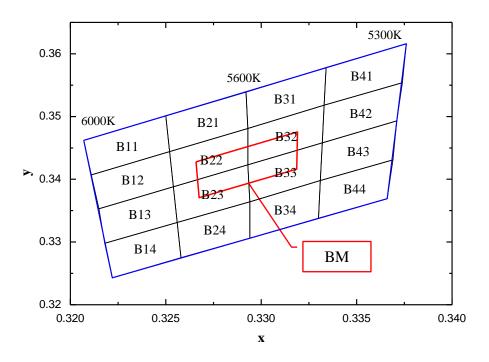


Fig 8. Radiant Pattern, T<sub>a</sub> =25 ℃

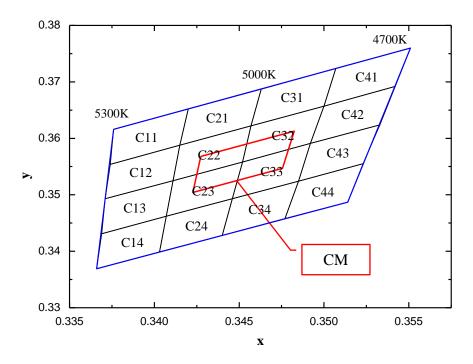




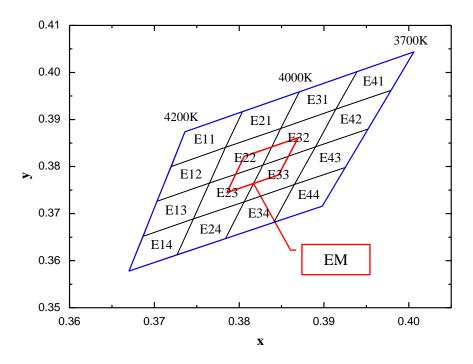
Bin	x	у	Bin	x	у	Bin	x	у
	0.3266	0.3428		0.3427	0.3568		0.3806	0.3822
ВМ	0.3268	0.3371	- - CM	0.3423	0.3504	ЕМ	0.3786	0.3745
DIVI	0.3319	0.3416	- CIVI	0.3476	0.3547	CIVI -	0.3846	0.3782
	0.3319	0.3476	-	0.3482	0.3613	,	0.3870	0.3861
	0.4336	0.4067		0.4581	0.4143			
GM	0.4294	0.3977	- нм	0.4531	0.4051			
GW	0.4354	0.3999	- пічі	0.4589	0.4065			
	0.4398	0.4089	-	0.4641	0.4157			



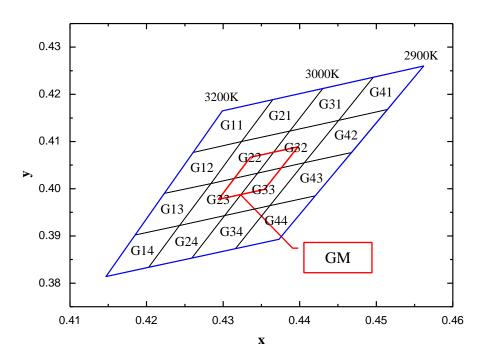
Bin	x	у	Bin	x	у	Bin	x	у	Bin	х	у
	0.3207	0.3462		0.3250	0.3501		0.3292	0.3539		0.3334	0.3578
B11	0.3211	0.3407	B21	0.3252	0.3444	B31	0.3293	0.3481	B41	0.3333	0.3518
611	0.3252	0.3444	DZI	0.3293	0.3481	D31	0.3333	0.3518	D41	0.3374	0.3554
	0.3250	0.3501		0.3292	0.3539		0.3334	0.3578		0.3376	0.3616
	0.3211	0.3407		0.3252	0.3444	B32 ·	0.3293	0.3481		0.3333	0.3518
B12	0.3215	0.3353	B22	0.3254	0.3388		0.3293	0.3423	B42	0.3332	0.3458
B12	0.3254	0.3388	BZZ	0.3293	0.3423		0.3332	0.3458		0.3371	0.3493
	0.3252	0.3444		0.3293	0.3481		0.3333	0.3518		0.3374	0.3554
	0.3215	0.3353		0.3254	0.3388		0.3293	0.3423	В43	0.3332	0.3458
B13	0.3218	0.3298	B23	0.3256	0.3331	B33	0.3294	0.3364		0.3331	0.3398
БІЗ	0.3256	0.3331	D23	0.3294	0.3364	DSS	0.3331	0.3398		0.3369	0.3431
	0.3254	0.3388		0.3293	0.3423		0.3332	0.3458		0.3371	0.3493
	0.3218	0.3298		0.3256	0.3331		0.3294	0.3364		0.3331	0.3398
B14	0.3222	0.3243	B24	0.3258	0.3275	B34	0.3294	0.3306	B44	0.3330	0.3338
	0.3258	0.3275	524	0.3294	0.3306	534	0.3330	0.3338		0.3366	0.3369
	0.3256		0.3294	0.3364		0.3331	0.3398		0.3369	0.3431	



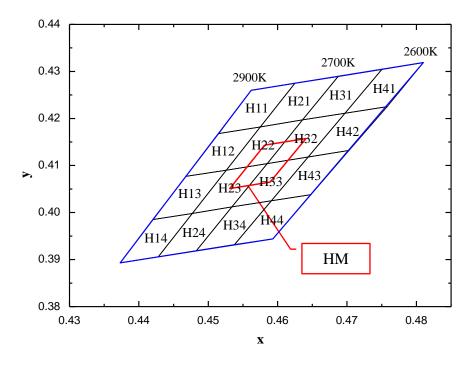
Bin	x	у									
	0.3376	0.3616		0.3420	0.3652		0.3463	0.3687		0.3507	0.3724
C11	0.3374	0.3554	C21	0.3415	0.3588	C31	0.3457	0.3622	C41	0.3500	0.3657
	0.3415	0.3588	GZI	0.3457	0.3622	CSI	0.3500	0.3657	C41	0.3542	0.3692
	0.3420	0.3652		0.3463	0.3687		0.3507	0.3724		0.3551	0.3760
	0.3374	0.3554		0.3415	0.3588	C32	0.3457	0.3622		0.3500	0.3657
C12	0.3371	0.3493	C22	0.3411	0.3525		0.3452	0.3558	C42	0.3492	0.3591
012	0.3411	0.3525	CZZ	0.3452	0.3558		0.3492	0.3591	C42	0.3533	0.3624
	0.3415	0.3588		0.3457	0.3622		0.3500	0.3657		0.3542	0.3692
	0.3371	0.3493		0.3411	0.3525	C33	0.3452	0.3558	C43	0.3492	0.3591
C13	0.3369	0.3431	C23	0.3407	0.3462		0.3446	0.3493		0.3485	0.3524
013	0.3407	0.3462	023	0.3446	0.3493	033	0.3485	0.3524		0.3523	0.3555
	0.3411	0.3525		0.3452	0.3558		0.3492	0.3591		0.3533	0.3624
	0.3369	0.3431		0.3407	0.3462		0.3446	0.3493		0.3485	0.3524
C14	0.3366	0.3369	C24	0.3403	0.3399	C34	0.3440	0.3428	C44	0.3477	0.3458
014	0.3403	0.3399	024	0.3440	0.3428	034	0.3477	0.3458		0.3514	0.3487
	0.3407	0.3462		0.3446	0.3493		0.3485	0.3524		0.3523	0.3555



Bin	x	у	Bin	x	у	Bin	x	у	Bin	х	у
	0.3736	0.3874		0.3804	0.3917		0.3871	0.3959		0.3939	0.4002
E11	0.3720	0.3800	E21	0.3784	0.3841	E31	0.3849	0.3881	E41	0.3914	0.3922
= ''	0.3784	0.3841	EZI	0.3849	0.3881	ESI	0.3914	0.3922	E41	0.3979	0.3962
	0.3804	0.3917		0.3871	0.3959		0.3939	0.4002		0.4006	0.4044
	0.3720	0.3800		0.3784	0.3841	E32	0.3849	0.3881		0.3914	0.3922
E12	0.3703	0.3726	E22	0.3765	0.3765		0.3828	0.3803	E42	0.3890	0.3842
	0.3765	0.3765	0.3828 0.3849	0.3828	0.3803		0.3890	0.3842	E42	0.3952	0.3880
	0.3784	0.3841		0.3881		0.3914	0.3922		0.3979	0.3962	
	0.3703	0.3726		0.3765	0.3765		0.3828	0.3803	E43	0.3890	0.3842
E13	0.3687	0.3652	E23	0.3746	0.3689	E33	0.3806	0.3725		0.3865	0.3762
	0.3746	0.3689	LZJ	0.3806	0.3725	E33	0.3865	0.3762		0.3925	0.3798
	0.3765	0.3765		0.3828	0.3803		0.3890	0.3842		0.3952	0.3880
	0.3687	0.3652		0.3746	0.3689		0.3806	0.3725		0.3865	0.3762
E14	0.3670	0.3578	E24	0.3727	0.3613	E34	0.3784	0.3647	E44	0.3841	0.3682
	0.3727	0.3613	L2 <del>7</del>	0.3784	0.3647	LJ4	0.3841	0.3682		0.3898	0.3716
	0.3746	0.3689		0.3806	0.3725		0.3865	0.3762		0.3925	0.3798

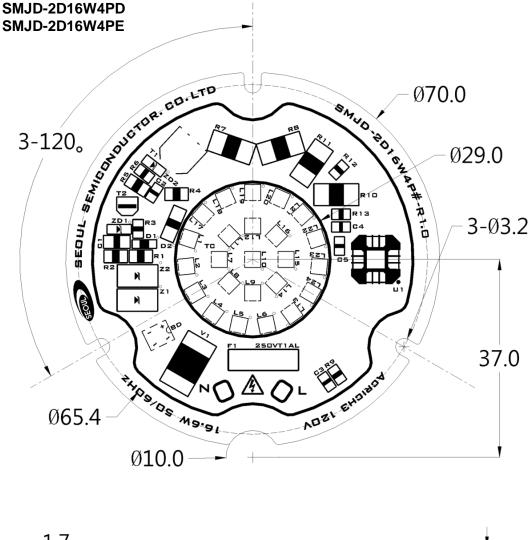


Bin	x	у	Bin	х	у	Bin	х	у	Bin	х	у
	0.4299	0.4165		0.4364	0.4188		0.4430	0.4212		0.4496	0.4236
G11	0.4261	0.4077	G21	0.4324	0.4099	G31	0.4387	0.4122	G41	0.4451	0.4145
911	0.4324	0.4100	GZI	0.4387	0.4122	GSI	0.4451	0.4145	G41	0.4514	0.4168
	0.4365	0.4189		0.4430	0.4212		0.4496	0.4236		0.4562	0.4260
	0.4261	0.4077		0.4324	0.4100	G32	0.4387	0.4122		0.4451	0.4145
G12	0.4223	0.3990	G22	0.4284	0.4011		0.4345	0.4033	G42	0.4406	0.4055
Giz	0.4284	0.4011	GZZ	0.4345	0.4033		0.4406	0.4055		0.4468	0.4077
	0.4324	0.4100		0.4387	0.4122		0.4451	0.4145		0.4515	0.4168
	0.4223	0.3990		0.4284	0.4011	G33	0.4345	0.4033	G43	0.4406	0.4055
G13	0.4185	0.3902	G23	0.4243	0.3922		0.4302	0.3943		0.4361	0.3964
013	0.4243	0.3922	G23	0.4302	0.3943	<b>G</b> 33	0.4361	0.3964		0.4420	0.3985
	0.4284	0.4011		0.4345	0.4033		0.4406	0.4055		0.4468	0.4077
	0.4243	0.3922		0.4302	0.3943		0.4302	0.3943		0.4361	0.3964
G14	0.4203	0.3834	G24	0.4259	0.3853	G34	0.4259	0.3853	G44	0.4316	0.3873
314	0.4147	0.3814	<b>G24</b>	0.4203	0.3834	<b>G</b> 34	0.4316	0.3873		0.4373	0.3893
	0.4185	0.3902		0.4243	0.3922		0.4361	0.3964		0.4420	0.3985



Bin	x	у	Bin	x	у	Bin	x	у	Bin	х	у
	0.4562	0.4260		0.4625	0.4275		0.4687	0.4289		0.4750	0.4304
H11	0.4515	0.4168	H21	0.4575	0.4182	H31	0.4636	0.4197	H41	0.4697	0.4211
"''	0.4575		П21	0.4636	0.4197	пэт	0.4697	0.4211	П41	0.4758	0.4225
	0.4625	0.4275		0.4687	0.4289		0.4750	0.4304		0.4810	0.4319
	0.4515	0.4168		0.4575	0.4182	H32	0.4636	0.4197		0.4697	0.4211
H12	0.4468	0.4077	H22	0.4526	0.4090		0.4585	0.4104	H42	0.4644	0.4118
1112	0.4526	0.4090		0.4585	0.4104		0.4644	0.4118	П42	0.4703	0.4132
	0.4575	0.4182		0.4636	0.4197		0.4697	0.4211		0.4758	0.4225
	0.4468	0.4077		0.4526	0.4090		0.4585	0.4104	Н43	0.4644	0.4118
H13	0.4420	0.3985	H23	0.4477	0.3998	H33	0.4534	0.4012		0.4591	0.4025
113	0.4477	0.3998	п23	0.4534	0.4012	поэ	0.4591	0.4025		0.4648	0.4038
	0.4526	0.4090		0.4585	0.4104		0.4644	0.4118		0.4703	0.4132
	0.4420	0.3985		0.4477	0.3998		0.4534	0.4012		0.4591	0.4025
H14	0.4373	0.3893	H24	0.4428	0.3906	H34	0.4483	0.3919	H44	0.4538	0.3932
""	0.4428	0.3906	1124	0.4483	0.3919	ПЭ4	0.4538	0.3932		0.4593	0.3944
	0.4477	4477 0.3998	0.4534	0.4012		0.4591	0.4025		0.4648	0.4038	

## **Mechanical Dimensions**





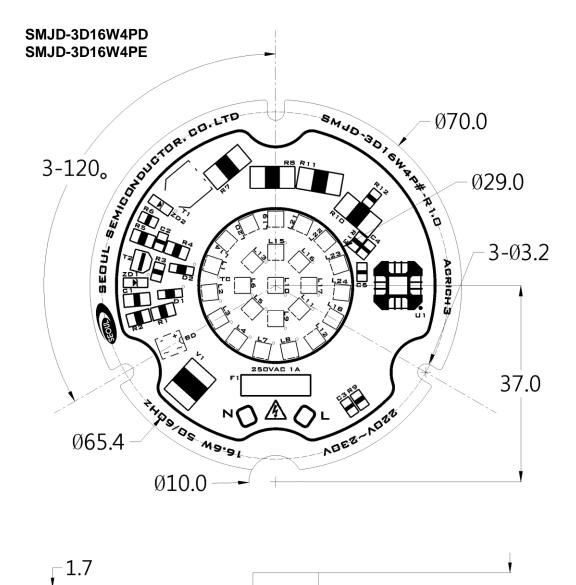
#### Notes:

(1) All dimensions are in millimeters. (Tolerance :  $\pm 0.2$ )

(2) Scale: None

4.7(Ref.)

## **Mechanical Dimensions**



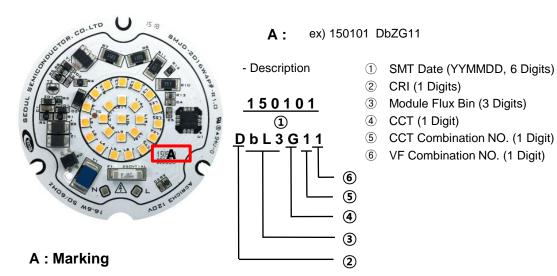
#### Notes

(1) All dimensions are in millimeters. (Tolerance :  $\pm 0.2$ )

(2) Scale: None



# **Marking Information**

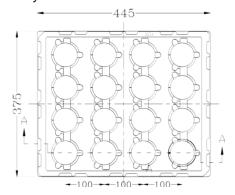


② CRI		③ Module Flux Bin			⊕ CCT			⑥ VF Bin			
Mark	CRI	Туре	Mark	Min.	Тур.	Mark	Bin A	Bin B	Mark	Min.	Max.
D	80	a	88	1250	1350	*0	*22	*33	1	D1	D1
E	90		99			*1	*23	*32	2	D1	D2
			11	1350	1450	*2	*33	*22	3	D2	D1
		b	33	1450	1600	*3	*32	*23	4	D1	D3
			55			*4	*MC	*MC	5	D3	D1
		С	77	1600	1750	*5	*22	*22	6	D2	D2
						*6	*23	*23	7	D2	D3
						*7	*32	*32	8	D3	D2
						*8	*33	*33	9	D3	D3
						*9	*22	*34			
						*A	*22	*43			
						*B	*22	*44			
						*C	*23	*31			
						*D	*23	*41			
						*E	*23	*42			
						*F	*32	*13			
						*G	*32	*14			
						*H	*32	*24			
						*I	*33	*11			
						*J	*33	*12			
						*H	*33	*21			

<sup>\*</sup> CCT Mark from \*0 to \*4 is 3-step

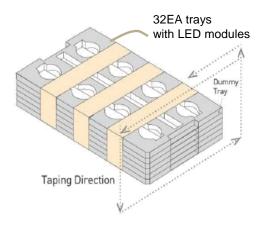
# **Packing**

### 1. Tray information



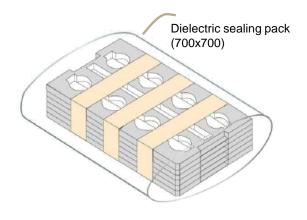
• 20 PCS LED modules packed per tray

### 2. Tray stack and taping

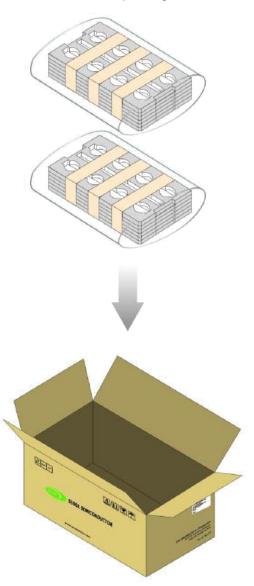


- 10 LED module trays and additional 1 dummy trays each up and down of box
- Add silica gel (1EA) on top of the tray

### 3. Sealing packing



### 4. Box information & packing



• Box Size : 590 x 330 x 165 mm

• 320 PCS modules per BOX 1EA

\*\* 1 Box : 32 PCS per tray x 10 trays = 320 PCS

### **Label Information**

Model No.	SMJD-XD16W4PX (1)				
Rank	XXXX16X <sup>(2)</sup>				
Туре	STD / 3-step <sup>(3)</sup>				
Quantity	XX 				
Date	YYMDDXXXXX-XXXXXXX				
SEOUL	SEOUL SEMICONDUCTOR CO.,LTD.				

#### **Notes**

(1) The model number designation is explained as follow

SMJD : Seoul Semiconductor internal code XD : Input Voltage ( 2D = 120V, 3D = 220V)

16W: About Power Consumption

4: Acrich IC Version 3.0

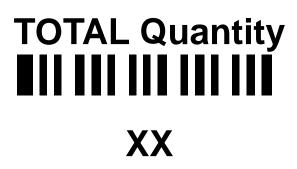
PX: MJT PKG (D=SAW8C72A, E=SAW9C72A)

(2) It represents the LED module rank.

XXX : ALL or Intensity Bin. X16 : CCT bin. (X = CCT)

X: A (Single bin) or M (Combination bin)

- (3) It represents All bin (STD) or MacAdam 3-Step (3-Step)
- (4) It is attached to the top of a sealing pack & the bottom right corner of the box.





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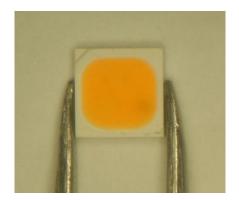
#### Notes

(1) It is attached to the bottom right corner of the box.



## **Handling of Silicone Resin for LEDs**





- (1) Acrich3 series is encapsulated with silicone resin for high optical efficiency.
- (2) Please do not touch the silicone resin area with sharp objects such as pincette(tweezers).
- (3) Finger prints on silicone resin area may affect the performance.
- (4) Please store LEDs in covered containers to prevent dust accumulation as this may affect performance.
- (5) Excessive force more than 3000gf to the silicone lens can result in fatal or permanent damage with LEDs.
- (6) Please do not cover the silicone resin area with any other resins such as epoxy, urethane, etc.

### **Precaution for Use**

- (1) Please review the Acrich3 Application Note for proper protective circuitry usage.
- (2) Please note, Acrich3 products run off of high voltage, therefore caution should be taken when working near Acrich3 products.
- (3) Make sure proper discharge prior to starting work.
- (4) DO NOT touch any of the circuit board, components or terminals with body or metal while circuit is active.
- (5) Please do not add or change wires while Acrich3 circuit is active.
- (6) Long time exposure to sunlight or UV can cause the lens to discolor.
- (7) Please do not use adhesives to attach the LED that outgas organic vapor.
- (8) Please do not use together with the materials containing Sulfur.
- (9) Please do not assemble in conditions of high moisture and/or oxidizing gas such as CI, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>x</sub>, etc.
- (10) Please do not make any modification on module.
- (11) Please be cautious when soldering to board so as not to create a short between different trace patterns.
- (12) Do not impact or place pressure on this product because even a small amount of pressure can damage the product. The product should also not be placed in high temperatures, high humidity or direct sunlight since the device is sensitive to these conditions.
- (13) When storing devices for a long period of time before usage, please following these guidelines:
  - \* The devices should be stored in the anti-static bag that it was shipped in from Seoul-Semiconductor with opening.
  - \* If the anti-static bag has been opened, re-seal preventing air and moisture from being present in the bag.
- (14) LEDs and IC are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). The acrich3 product should also not be installed in end equipment without ESD protection. Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.
- a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

### **Precaution for Use**

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event. One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

#### Environmental controls:

- Humidity control (ESD gets worse in a dry environment)

#### b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device. The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package
  (If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package (shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires
- This damage usually appears due to the thermal stress produced during the EOS event
- c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:
  - A surge protection circuit
  - An appropriately rated over voltage protection device
  - A current limiting device



## **Company Information**

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#### **Company Information**

Seoul Semiconductor (www.SeoulSemicon.com) manufacturers and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

#### **Legal Disclaimer**

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